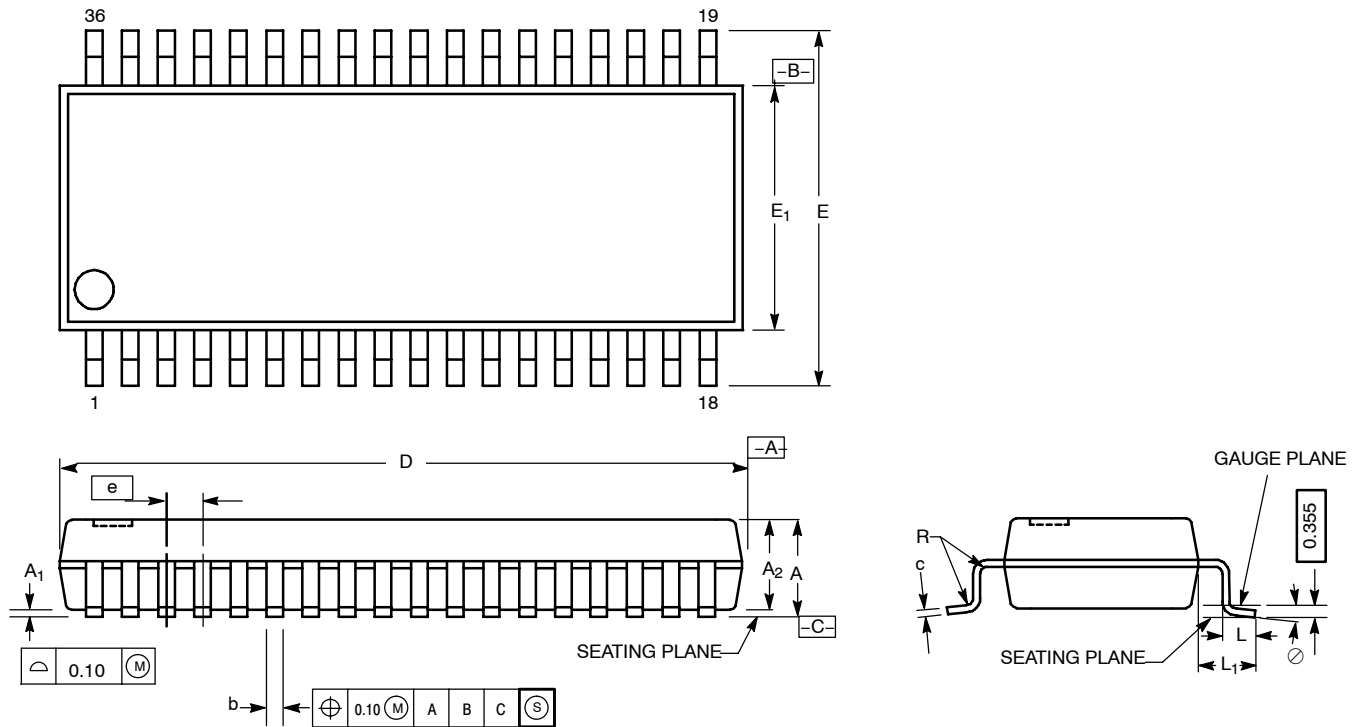


QSOP: 36-LEAD (7.5 mm) (POWER IC ONLY)



NOTES:

1. Package surface finishing: All sides #27~30.
2. All dimensions excluding mold flashes.
3. End flash from the package body shall not exceed 0.152 (0.006") per side D.
4. Dimension b does not include dambar protrusion/intrusion and solder coverage.

Dim	MILLIMETERS		
	Min	Nom	Max
A	2.44	2.54	2.64
A ₁	0.10	0.20	0.30
A ₂	2.34	2.34	2.34
b	0.28	0.40	0.51
c	0.23	0.28	0.32
D	15.20	15.30	15.40
E	10.11	10.31	10.51
E ₁	7.40	7.50	7.60
e	0.80 BSC		
L	0.40	0.84	0.127
L ₁	1.41 BSC		
R	0.15	0.20	0.25
∅	0°	4°	8°
ECN: S-41147—Rev. A, 14-Jun-04			
DWG: 5936			